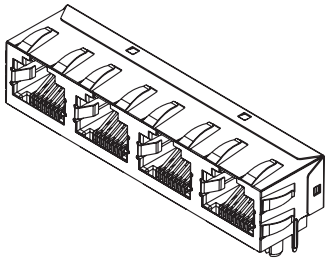
Jameco Part Number 1970906

Modular Jack

44248

Ganged, Right Angle
Low Profile Inverted
Shielded and Unshielded Versions



Features and Benefits
- Plug latch on top
- Shortened leads with bottom contacts
- Industry compatible
- Enhanced panel grounding tabs on shield
- Shielding meets IEC 950, UL 1863 and CSA 233

Reference Information
Product Specification: PS-43860-003
Packaging: Tray
UL File No.: E107635
CSA File No.: LR19980
Designed In: Inches

Electrical
Voltage: 125V
Current: 1.5A
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 1000V AC
Insulation Resistance: 500 Megohms min.

Mechanical
Durability: 500 cycles

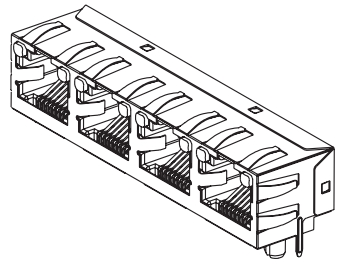
Physical
Housing: Black glass-filled Polyester, UL 94V-0
Contact: Phosphor Bronze
Plating: Contact Area—1.27µm (50µ") min. Gold
Solder Tails—2.54µm (100µ") min. Tin,
Nickel overall
Operating Temperature: -40 to +85˚C

Circuits	Loaded Contacts	No. of Ports	Order No.				Lead-free
			Unshielded		Shielded		
			Press Fit	Snap Fit	Press Fit	Snap Fit	
6	4	2	44248-0074	44248-0066	44248-0102	44248-0094	Yes
	6		44248-0073	44248-0065	44248-0101	44248-0093	
8	8	2	44248-0061	44248-0057	44248-0089	44248-0085	
		4	44248-0062	44248-0058	44248-0090	44248-0086	

Modular Jack

44248

Ganged, Right Angle
Low Profile Inverted
Shielded and Unshielded Versions
With Lightpipes



Features and Benefits
- Plug latch on top
- Industry compatible
- Lower electrical noise than LED offerings
- 34% fewer leads than LED offerings
- Enhanced panel grounding tabs on shield

Reference Information
Product Specification: PS-43860-003
Packaging: Tray
UL File No.: E107635
CSA File No.: LR19980
Designed In: Inches

Electrical
Voltage: 125V
Current: 1.5A
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 1000V AC
Insulation Resistance: 500 Megohms min.

Mechanical
Durability: 500 cycles

Physical
Housing: Black glass-filled Polyester, UL 94V-0
Contact: Phosphor Bronze
Plating: Contact Area—1.27µm (50µ") min. Gold
Solder Tails—2.54µm (100µ") min. Tin,
Nickel overall
Operating Temperature: -40 to +85˚C

Circuits	Loaded Contacts	No. of Ports	Order No.				Lead-free
			Unshielded		Shielded		
			Press Fit	Snap Fit	Press Fit	Snap Fit	
6	4	2	44248-0018	44248-0010	44248-0046	44248-0038	Yes
	6		44248-0017	44248-0009	44248-0045	44248-0037	
8	8	2	44248-0005	44248-0001	44248-0033	44248-0029	
		4	44248-0006	44248-0002	44248-0034	44248-0030	

PRODUCT SPECIFICATION

INVERTED RIGHT ANGLE MODULAR JACKS

1.0 SCOPE

This Product Specification covers the 1.02 mm (.040 inch) centerline (pitch) printed circuit board (PCB) modular jack connector series with selective gold and tin plating.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER(S)

Single Port Inverted Modular Jack	43860
Single Port Inverted Mini-PCI Modular Jack	44380
Dual Port Inverted Modular Jack	43814
Ganged Inverted Modular Jack	44248
Single Port Inverted Modular Jack with Keep-out Feature	44620

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See the appropriate sales drawings (SD-43860-001, SD-44380-001, SD-43814-001, SD-44248-001) for information on dimensions, materials, plating and markings.

2.3 SAFETY AGENCY APPROVALS

UL File Number……E107635
CSA File Number……..LR19980

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

FCC Rules and Regulations, Part 68, Subpart F
REA Bulletin 345-81, PE-76; Specification for modular telephone set hardware
ANSI/EIA/TIA-568
IEC-60603-7
UL 1863
MIL-STD-202; General requirements for test specifications

4.0 RATINGS

4.1 VOLTAGE

56.5 V DC
150 V_{RMS} AC (Ringing voltage only)

4.2 CURRENT

1.5 Amps @ 25°C

4.3 TEMPERATURE

Operating: - 40°C to + 85°C
Nonoperating:* - 40°C to + 85°C
*Packaging materials should not exceed + 50°C

5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

	DESCRIPTION	TEST CONDITION	REQUIREMENT
	Contact Resistance (Low Level)	Mate connectors: apply a maximum voltage of **20** mV and a current of **100** mA. (Measurement locations in Section 7.0)	**20** milliohms MAXIMUM [initial]
	Insulation Resistance	Unmated connector, mounted to a PCB: apply a voltage of **100** VDC between adjacent terminals and between terminals to ground.	**500** Megohms MINIMUM
	Dielectric Withstanding Voltage	Mate connectors: apply a voltage of **1000** VAC for **1** minute between adjacent terminals and between terminals to ground.	No breakdown; current leakage < **5** mA

5.2 MECHANICAL REQUIREMENTS

	DESCRIPTION	TEST CONDITION	REQUIREMENT
	Connector Mate Force	Mate connector at a rate of **25 ± 6** mm (**1 ± ¼** inch) per minute. (Gage dimensions in Section 7.0)	**22** N (**5** lbf) unshielded MAXIMUM insertion force **35** N (**8** lbf) shielded MAXIMUM insertion force
	Durability	Mate connectors up to **500** cycles at a maximum rate of **10** cycles per minute prior to Environmental Tests.	**10** milliohms MAXIMUM (change from initial)
	Vibration (Random)	Amplitude: 1.50mm (.060") peak to peak Sweep: 10-55-10 Hz in one minute Duration: 15 minutes ±X,±Y,±Z axis (45 minutes total)	**10** milliohms MAXIMUM (change from initial) & Discontinuity < **1** microsecond
	Plug Retention Force	Apply an axial pullout force on the plug at a rate of **25 ± 6** mm (**1 ± ¼** inch) per minute.	**89** N (**20** lbf) MINIMUM retention force
	PCB Separation Forces	Apply a perpendicular load on the plug at a rate of **25 ± 6** mm (**1 ± ¼** inch) per minute.	**4.5** N (**1** lbf) MINIMUM withdrawal force before solder reflow **89** N (**20** lbf) MINIMUM withdrawal force after solder reflow
	Shock (Mechanical)	Mate connectors and shock at **50** g's with three saw tooth wave form shocks in the ±X,±Y,±Z axis (18 shocks total).	**10** milliohms MAXIMUM (change from initial) & Discontinuity < **1** microsecond

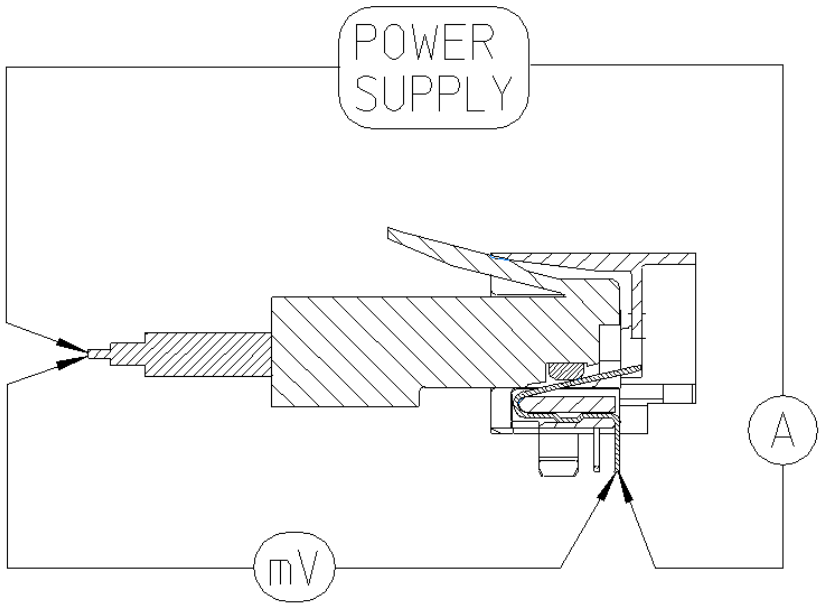
5.3 ENVIRONMENTAL REQUIREMENTS

	DESCRIPTION	TEST CONDITION	REQUIREMENT
	Shock (Thermal)	Mate connectors; expose to **10** cycles of: **-40**°C to +**85**°C **30** minutes dwell	**10** milliohms MAXIMUM (change from initial) & Visual: No Damage
	Thermal Aging	Mate connectors; expose to: **240** hours at **85±2**°C	**10** milliohms MAXIMUM (change from initial) & Visual: No Damage
	Humidity (Cyclic)	Mate connectors: expose to **10** cycles at **90-95**% relative humidity with temperatures at +**25**°C and +**65**°C per MIL-STD-202F method 106F (without -10°C dip)	**10** milliohms MAXIMUM (change from initial) & Dielectric Withstanding Voltage: No Breakdown at **500** VAC & Insulation Resistance: **200** Megohms MINIMUM & Visual: No Damage
	Solder Resistance	Dip connector terminal tails in solder: Solder Duration: **7±0.5** seconds Solder Temperature: **260±5**°C **{**Recommended same parameters as **SMES-152.}** Note: The solder resistance test simulates a wave solder process. This test should not be used to determine the suitability of the connector for a convection or IR reflow solder process.	Visual: No Damage to insulator material

6.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage. See appropriate sales drawings on Sheet 1 for packaging descriptions.

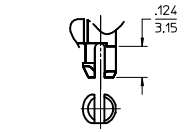
7.0 GAGES AND FIXTURES



TERMINATION RESISTANCE MEASUREMENT POINTS
Connector and plug terminals and wire conductor bulk resistance to be subtracted from measurements

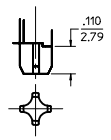
8.0 OTHER INFORMATION

8 CIRCUIT HOUSING(S)						
ASSEMBLY MATERIAL NUMBER	NUMBER OF CIRCUITS	NUMBER OF PORTS	PEG STYLE	DIM -A-	DIM -B-	DIM -C-
44248-0001	8	2	SNAP-FIT	1.250/31.75	1.120/28.45	.469/11.92
44248-0002	8	4	SNAP-FIT	2.490/63.25	2.360/59.94	.469/11.92
44248-0005	8	2	PRESS-FIT	1.250/31.75	1.120/28.45	.469/11.92
44248-0006	8	4	PRESS-FIT	2.490/63.25	2.360/59.94	.469/11.92



SNAP-FIT PEG OPTION

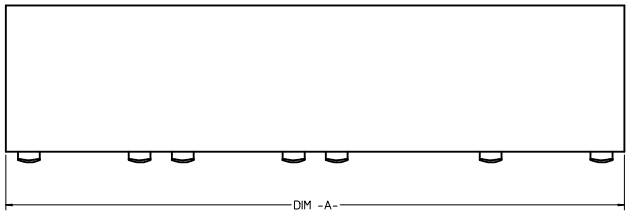
SCALE: NTS
SEE NOTE #8

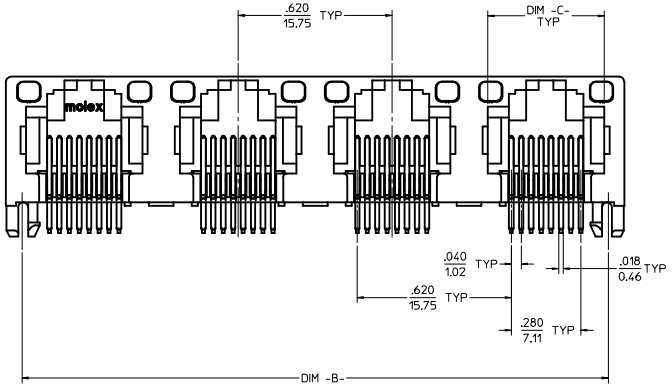


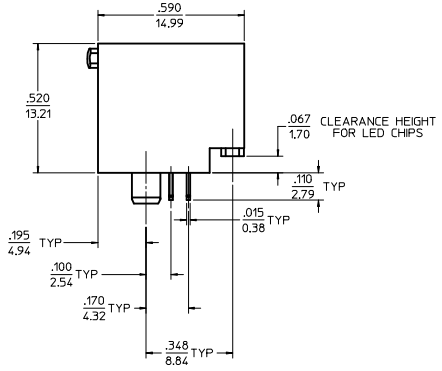
PRESS-FIT PEG OPTION

SCALE: NTS
SEE NOTE #8

6 CIRCUIT HOUSING(S)						
ASSEMBLY MATERIAL NUMBER	NUMBER OF CIRCUITS	NUMBER OF PORTS	PEG STYLE	DIM -A-	DIM -B-	DIM -C-
44248-0009	6	2	SNAP-FIT	1.250/31.75	1.120/28.45	.389/9.88
44248-0010	4	2	SNAP-FIT	1.250/31.75	1.120/28.45	.389/9.88
44248-0011	6	4	SNAP-FIT	2.490/63.25	2.360/59.94	.389/9.88
44248-0012	4	4	SNAP-FIT	2.490/63.25	2.360/59.94	.389/9.88
44248-0017	6	2	PRESS-FIT	1.250/31.75	1.120/28.45	.389/9.88
44248-0018	4	2	PRESS-FIT	1.250/31.75	1.120/28.45	.389/9.88
44248-0019	6	4	PRESS-FIT	2.490/63.25	2.360/59.94	.389/9.88
44248-0020	4	4	PRESS-FIT	2.490/63.25	2.360/59.94	.389/9.88







NOTES:
1) MATERIAL:
HOUSING: POLYESTER(PBT), GLASS FILLED, UL94V-0, COLOR: BLACK
LIGHT PIPES: POLYCARBONATE, UL-94V2, COLOR: CLEAR
TERMINALS: PHOSPHOR BRONZE
2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS.
3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-44248-004.
5) APPLICATION SPECIFICATION: AS-43860-001
6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
7) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
8) MODJACKS AVAILABLE WITH EITHER SNAP-FIT OR PRESS-FIT PEGS.
THIS DRAWING SHOWS SNAP-FIT PEGS.
9) PCB LAYOUT AND PANEL CUT-OUT SHOWN ON SHEETS (5) AND (6).
10) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

UNSHIELDED
WITH LIGHT PIPES

CHGD 0117 TO 0119
EC NO: UCP2009-1482
DRWN: IKLOSTEMEIER 2008/12/10
CH'KD: JBELL 2008/12/10
APPR: FSMITH 2008/12/10
DESCRIPTION
REV
C4

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

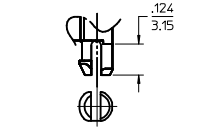
DRAWN BY: MMAYO DATE: 98/10/06
CHECKED BY: JROBERTS DATE: 98/10/06
APPROVED BY: JROBERTS DATE: 98/10/06

TITLE: GANGED INVERTED MODJACK ASSEMBLY

MOLEX INCORPORATED

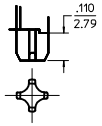
MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-44248-001
SHEET NO.: 1 OF 6

SIZE: D



SNAP-FIT PEG OPTION

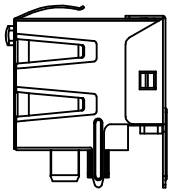
SCALE: NTS
SEE NOTE #8



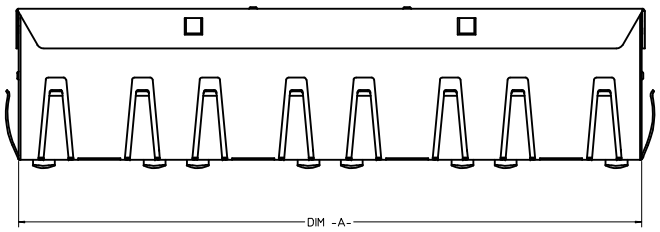
PRESS-FIT PEG OPTION

SCALE: NTS
SEE NOTE #8

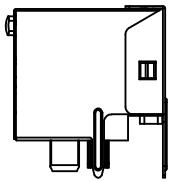
SIDE SHIELD
TAB OPTION A



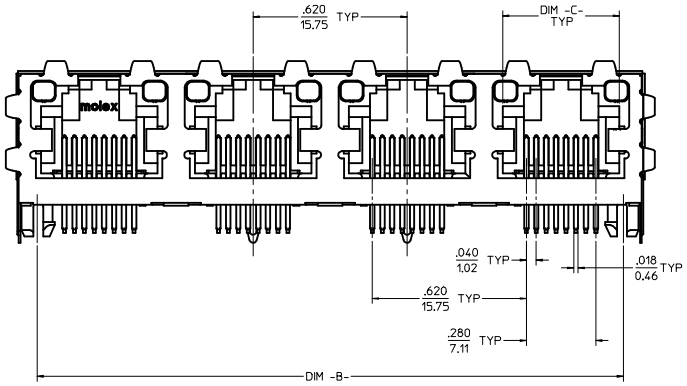
(8) CIRCUIT HOUSING(S)							
ASSEMBLY MATERIAL NUMBER	NUMBER OF CIRCUITS	NUMBER OF PORTS	PEG STYLE	SIDE SHIELD TAB OPTION	DIM -A-	DIM -B-	DIM -C-
44248-0029	8	2	SNAP-FIT	A	1.274/32.36	1.120/28.45	.469/11.92
44248-0030	8	4	SNAP-FIT	A	2.514/63.86	2.360/59.94	.469/11.92
44248-0033	8	2	PRESS-FIT	A	1.274/32.36	1.120/28.45	.469/11.92
44248-0034	8	4	PRESS-FIT	A	2.514/63.86	2.360/59.94	.469/11.92

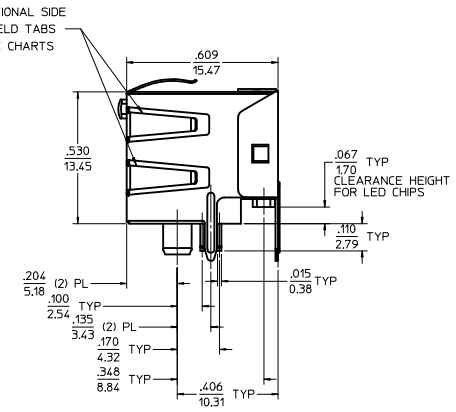


SIDE SHIELD
TAB OPTION B



(6) CIRCUIT HOUSING(S)							
ASSEMBLY MATERIAL NUMBER	NUMBER OF CIRCUITS	NUMBER OF PORTS	PEG STYLE	SIDE SHIELD TAB OPTION	DIM -A-	DIM -B-	DIM -C-
44248-0037	6	2	SNAP-FIT	A	1.274/32.36	1.120/28.45	.389/9.88
44248-0038	4	2	SNAP-FIT	A	1.274/32.36	1.120/28.45	.389/9.88
44248-0039	6	4	SNAP-FIT	A	2.514/63.86	2.360/59.94	.389/9.88
44248-0040	4	4	SNAP-FIT	A	2.514/63.86	2.360/59.94	.389/9.88
44248-0045	6	2	PRESS-FIT	A	1.274/32.36	1.120/28.45	.389/9.88
44248-0046	4	2	PRESS-FIT	A	1.274/32.36	1.120/28.45	.389/9.88
44248-0047	6	4	PRESS-FIT	A	2.514/63.86	2.360/59.94	.389/9.88
44248-0048	4	4	PRESS-FIT	A	2.514/63.86	2.360/59.94	.389/9.88





NOTES:
1) MATERIAL:
   HOUSING: POLYESTER(PBT), GLASS FILLED, UL94V-0, COLOR: BLACK
   LIGHT PIPES: POLYCARBONATE, UL-94V2, COLOR: CLEAR
   TERMINALS: PHOSPHOR BRONZE
   SHIELD: BRASS
2) FINISH:
   TERMINALS:
   SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN..
   *SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN., WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
   SHIELD:
   *100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES (1.27 MICROMETERS) COPPER UNDERPLATE PCB GROUND TABS DIPPED IN TIN
   *THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
4) PACKAGING SPECIFICATION:
   CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-44248-004.
5) APPLICATION SPECIFICATION: AS-43860-001
6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
7) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
8) MODJACKS AVAILABLE WITH EITHER SNAP-FIT OR PRESS-FIT PEGS. THIS DRAWING SHOWS SNAP-FIT PEGS.
9) PCB LAYOUT AND PANEL CUT-OUT SHOWN ON SHEETS (5) AND (6).
10 THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

SHIELDED
WITH LIGHT PIPES

SEE SHEET 1
EC NO: UCP2009-1482
DRWN: JKLOSTERMEIER 2008/12/10
CH'KD: JBELL 2008/12/10
APPR: FSMITH 2008/12/10
DESCRIPTION
C4
REV

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

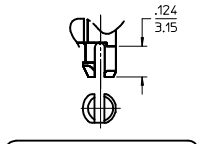
DRAWN BY: MMAYO DATE: 98/10/06
CHECKED BY: JROBERTS DATE: 98/10/06
APPROVED BY: JROBERTS DATE: 98/10/06

TITLE: GANGED INVERTED MODJACK ASSEMBLY

MOLEX INCORPORATED

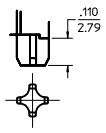
MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-44248-001
SHEET NO.: 2 OF 6

SIZE: D



SNAP-FIT PEG OPTION

SCALE: NTS
SEE NOTE #7

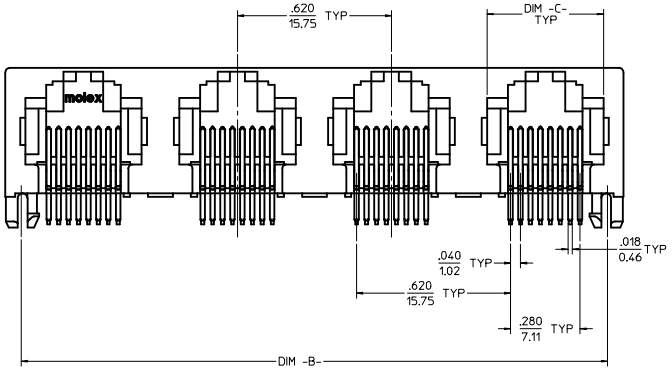


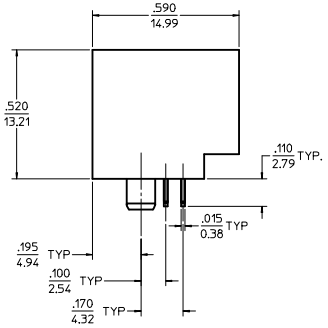
PRESS-FIT PEG OPTION

SCALE: NTS
SEE NOTE #7

8 CIRCUIT HOUSING(S)						
ASSEMBLY MATERIAL NUMBER	NUMBER OF CIRCUITS	NUMBER OF PORTS	PEG STYLE	DIM -A-	DIM -B-	DIM -C-
44248-0057	8	2	SNAP-FIT	1.250/31.75	1.120/28.45	.469/11.92
44248-0058	8	4	SNAP-FIT	2.490/63.25	2.360/59.94	.469/11.92
44248-0061	8	2	PRESS-FIT	1.250/31.75	1.120/28.45	.469/11.92
44248-0062	8	4	PRESS-FIT	2.490/63.25	2.360/59.94	.469/11.92

6 CIRCUIT HOUSING(S)						
ASSEMBLY MATERIAL NUMBER	NUMBER OF CIRCUITS	NUMBER OF PORTS	PEG STYLE	DIM -A-	DIM -B-	DIM -C-
44248-0065	6	2	SNAP-FIT	1.250/31.75	1.120/28.45	.389/9.88
44248-0066	4	2	SNAP-FIT	1.250/31.75	1.120/28.45	.389/9.88
44248-0067	6	4	SNAP-FIT	2.490/63.25	2.360/59.94	.389/9.88
44248-0068	4	4	SNAP-FIT	2.490/63.25	2.360/59.94	.389/9.88
44248-0073	6	2	PRESS-FIT	1.250/31.75	1.120/28.45	.389/9.88
44248-0074	4	2	PRESS-FIT	1.250/31.75	1.120/28.45	.389/9.88
44248-0075	6	4	PRESS-FIT	2.490/63.25	2.360/59.94	.389/9.88
44248-0076	4	4	PRESS-FIT	2.490/63.25	2.360/59.94	.389/9.88





NOTES:
1) MATERIAL:
HOUSING: POLYESTER(PBT), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS.
3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-44248-004.
5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
7) MODJACKS AVAILABLE WITH EITHER SNAP-FIT OR PRESS-FIT PEGS.
THIS DRAWING SHOWS SNAP-FIT PEGS.
8) PCB LAYOUT AND PANEL CUT-OUT SHOWN ON SHEETS (5) AND (6).
9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

UNSHIELDED

SEE SHEET 1
EC NO: UCP2009-1482
DRWN: JKLOSTERMEIER 2008/12/10
CH'KD: JBELL 2008/12/10
APPR: FSMITH 2008/12/10
DESCRIPTION
REV
C4

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

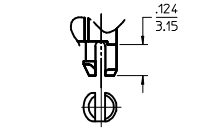
DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY	MMAYO	DATE 98/10/06
CHECKED BY	JROBERTS	DATE 98/10/06
APPROVED BY	JROBERTS	DATE 98/10/06

TITLE: GANGED INVERTED MODJACK ASSEMBLY

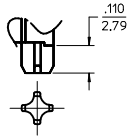
MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-44248-001
SHEET NO.: 3 OF 6
SIZE: D



SNAP-FIT PEG OPTION

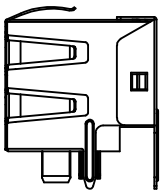
SCALE: NTS
SEE NOTE #7



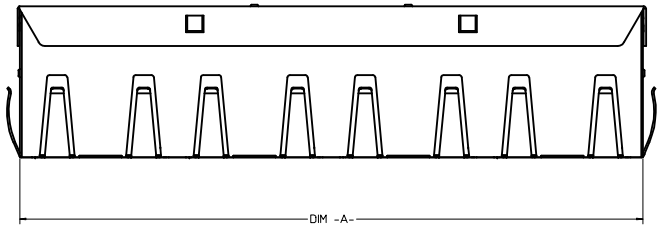
PRESS-FIT PEG OPTION

SCALE: NTS
SEE NOTE #7

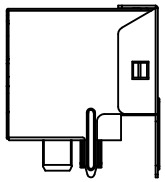
SIDE SHILED
TAB OPTION A



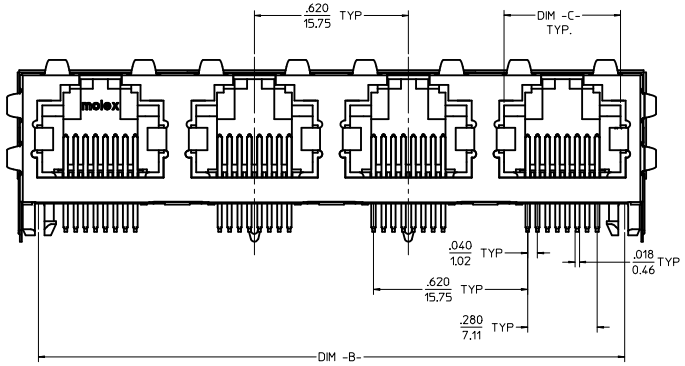
(8) CIRCUIT HOUSING(S)								
X = NOT TOOLED	ASSEMBLY MATERIAL NUMBER	NUMBER OF CIRCUITS	NUMBER OF PORTS	PEG STYLE	SIDE SHIELD TAB OPTION	DIM -A-	DIM -B-	DIM -C-
	44248-0085	8	2	SNAP-FIT	A	1.274/32.36	1.120/28.45	.469/11.92
	44248-0086	8	4	SNAP-FIT	A	2.514/63.86	2.360/59.94	.469/11.92
	44248-0089	8	2	PRESS-FIT	A	1.274/32.36	1.120/28.45	.469/11.92
	44248-0090	8	4	PRESS-FIT	A	2.514/63.86	2.360/59.94	.469/11.92
X	44248-0119	8	4	PRESS FIT	B	2.514/63.86	2.360/59.94	.469/11.92

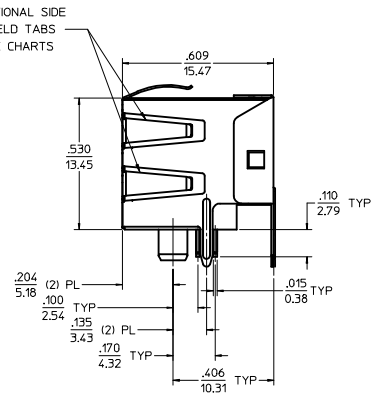


SIDE SHILED
TAB OPTION B



(6) CIRCUIT HOUSING(S)							
ASSEMBLY MATERIAL NUMBER	NUMBER OF CIRCUITS	NUMBER OF PORTS	PEG STYLE	SIDE SHIELD TAB OPTION	DIM -A-	DIM -B-	DIM -C-
44248-0093	6	2	SNAP-FIT	A	1.274/32.36	1.120/28.45	.389/9.88
44248-0094	4	2	SNAP-FIT	A	1.274/32.36	1.120/28.45	.389/9.88
44248-0095	6	4	SNAP-FIT	A	2.514/63.86	2.360/59.94	.389/9.88
44248-0096	4	4	SNAP-FIT	A	2.514/63.86	2.360/59.94	.389/9.88
44248-0101	6	2	PRESS-FIT	A	1.274/32.36	1.120/28.45	.389/9.88
44248-0102	4	2	PRESS-FIT	A	1.274/32.36	1.120/28.45	.389/9.88
44248-0103	6	4	PRESS-FIT	A	2.514/63.86	2.360/59.94	.389/9.88
44248-0104	4	4	PRESS-FIT	A	2.514/63.86	2.360/59.94	.389/9.88





NOTES:
1) MATERIAL:
HOUSING: POLYESTER(PBT), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
SHIELD: BRASS
2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
SHIELD:
*100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES (1.27 MICROMETERS)
COPPER UNDERPLATE PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-44248-004.
5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
7) MODJACKS AVAILABLE WITH EITHER SNAP-FIT OR PRESS-FIT PEGS.
THIS DRAWING SHOWS SNAP-FIT PEGS.
8) PCB LAYOUT AND PANEL CUT-OUT SHOWN ON SHEETS (5) AND (6).
9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

SHIELDED

CHGD 0117 TO 0119
EC NO: UCP2009-1482
DRWN: KLOSTERMEIER 2008/12/10
CHKD: JBELL 2008/12/10
APPR: FSMITH 2008/12/10
DESCRIPTION
REV
C4

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

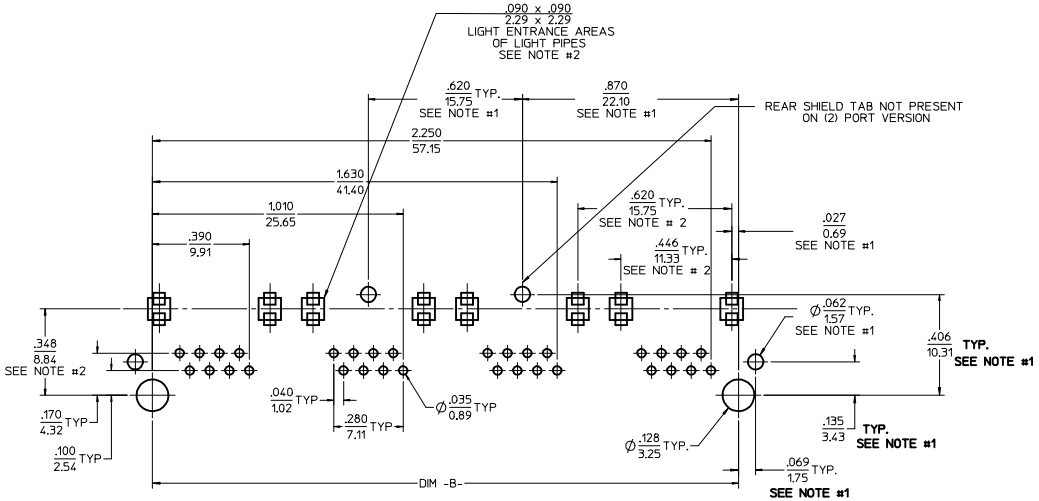
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

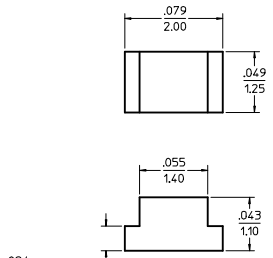
DRAWN BY	MMAYO
DATE	98/10/06
CHECKED BY	JROBERTS
DATE	98/10/06
APPROVED BY	JROBERTS
DATE	98/10/06
MATERIAL NO.	SEE CHART
DOCUMENT NO.	SD-44248-001
SHEET NO.	4 OF 6
SIZE	D

TITLE: GANGED INVERTED MODJACK ASSEMBLY

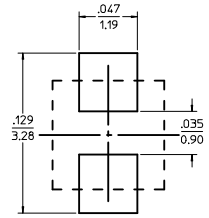
MOLEX INCORPORATED



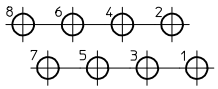
8 CIRCUIT PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: .062/1.57
TOLERANCE ±.003/.076 UNLESS OTHERWISE SPECIFIED



RECOMMENDED SMT
LED DIMENSIONS
SCALE: NTS
(SEE NOTE 3)



RECOMMENDED SMT
LED SOLDER PATTERN
SCALE: NTS



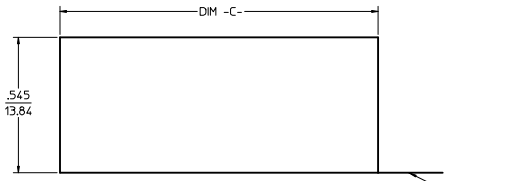
TYPICAL PC TERMINAL HOLE LAYOUT
(8) CIRCUIT CONFIGURATION
SCALE: 10:1

NOTES:

1) DIMENSIONS MARKED "SEE NOTE #1" REFER TO ASSEMBLIES WITH THE SHIELDING OPTION INCLUDED

2) DIMENSIONS MARKED "SEE NOTE #2" REFER TO ASSEMBLIES WITH THE LIGHT PIPE OPTION INCLUDED

3) FOR CROSS REFERENCE OF RECOMMENDED LEDS SEE MOLEX WEB SITE.



RECOMMENDED PANEL CUTOUT

NUMBER OF PORTS	DIM -B-	DIM -C-
2	1.120/28.45	1.280/32.51
4	2.360/59.94	2.520/64.01

SEE SHEET 1
EC NO: UCP2009-1482 2008/12/10
DRWN: JKLOSTEMEIER 2008/12/10
CHKD: JBELL 2008/12/10
APPR: FSMITH 2008/12/10
DESCRIPTION
C4
REV

QUALITY SYMBOLS
▼=0
▽=0

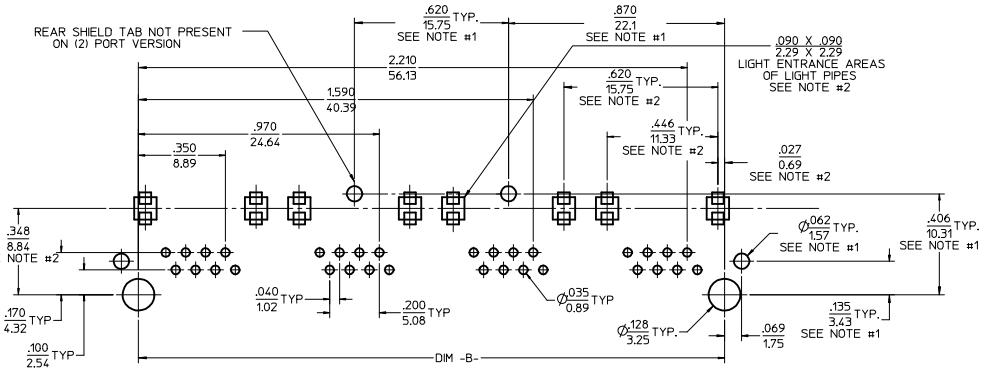
GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

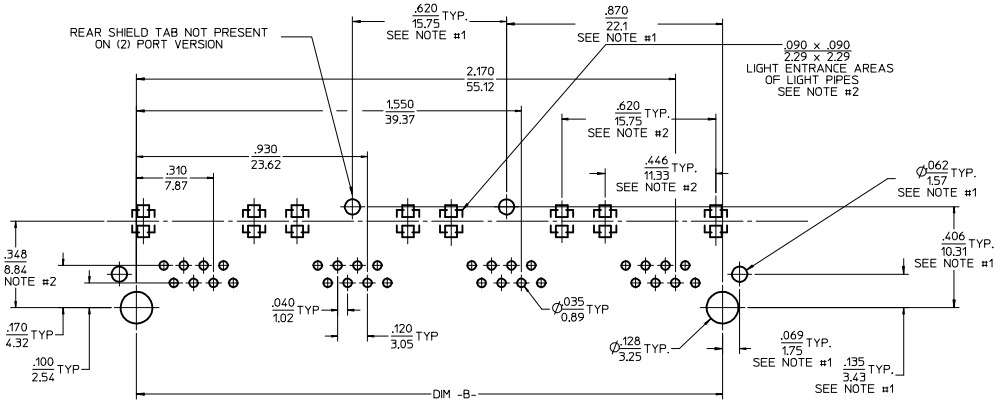
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM	SCALE: 4:1	DESIGN UNITS: INCH	THIRD ANGLE PROJECTION
DRAWN BY: MMAYO	DATE: 98/10/06	TITLE: GANGED INVERTED MODJACK ASSEMBLY	
CHECKED BY: JROBERTS	DATE: 98/10/06		
APPROVED BY: JROBERTS	DATE: 98/10/06	molex MOLEX INCORPORATED	
MATERIAL NO.: N/A		DOCUMENT NO.: SD-44248-001	SHEET NO.: 5 OF 6

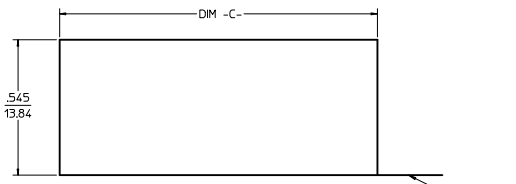
SIZE D



6 CIRCUIT PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: .062/1.57
TOLERANCE ±.003/.076 UNLESS OTHERWISE SPECIFIED

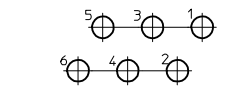


4 CIRCUIT PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: .062/1.57
TOLERANCE ±.003/.076 UNLESS OTHERWISE SPECIFIED

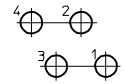


RECOMMENDED PANEL CUTOUT

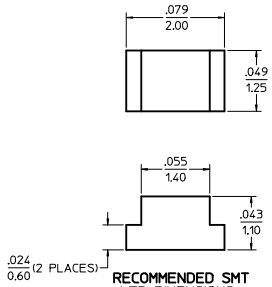
NUMBER OF PORTS	DIM -B-	DIM -C-
2	1.120/28.45	1.280/32.51
4	2.360/59.94	2.520/64.01



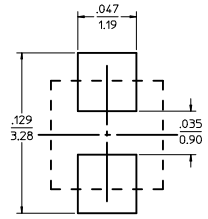
TYPICAL PC TERMINAL HOLE LAYOUT
(6) CIRCUIT CONFIGURATION
SCALE: 10:1



TYPICAL PC TERMINAL HOLE LAYOUT
(4) CIRCUIT CONFIGURATION
SCALE: 10:1



RECOMMENDED SMT
LED DIMENSIONS
SCALE: NTS
(SEE NOTE 3)



RECOMMENDED SMT
LED SOLDER PATTERN
SCALE: NTS

NOTES:

1) DIMENSIONS MARKED "SEE NOTE #1" REFER TO ASSEMBLIES WITH SHIELDING OPTION INCLUDED

2) DIMENSIONS MARKED "SEE NOTE #2" REFER TO ASSEMBLIES WITH THE LIGHT PIPE OPTION INCLUDED

3) FOR CROSS REFERENCE OF RECOMMENDED LEDS SEE MOLEX WEB SITE.

SEE SHEET 1
EC NO: UCP2009-1482
DRWN: KLOSTEMEIER 2008/12/10
CHKD: JBELL 2008/12/10
APPR: SMITH 2008/12/10
DESCRIPTION
REV
C4

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: MMAYO DATE: 98/10/06
CHECKED BY: JROBERTS DATE: 98/10/06
APPROVED BY: JROBERTS DATE: 98/10/06

TITLE: GANGED INVERTED MODJACK ASSEMBLY

MOLEX INCORPORATED

MATERIAL NO.: N/A
DOCUMENT NO.: SD-44248-001
SHEET NO.: 6 OF 6
SIZE: D